



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re application of: Chien-Chao Huang et al.
Serial No.: **10/627,849**

Examiner: **Unknown**
Confirmation No.: **2641**

Filed: **July 25, 2003**

Attorney Docket No.: **N1085-00151**

For: **SEMICONDUCTOR DEVICE WITH MODIFIED CHANNEL COMPRESSIVE STRESS AND THE METHOD FOR MAKING SAME**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

This Information Disclosure Statement is being filed in connection with the patent application referenced above. The Examiner is requested to consider each of the references cited herein and forward an initialed copy of the enclosed PTO Form 1449 to the undersigned representative. This Statement is being filed:

- Upon filing the application.
- Within three months from the filing date of this application, which is not a continued prosecution application.
- Before the mailing date of a first Office action on the merits for this application.
- Before the mailing date of a first Office action after the filing of a request for continued examination.
- Before the mailing date of any of: (i) a Final Office Action, (ii) a Notice of Allowance, and (iii) any other action that closes prosecution of this application. The Statement is accompanied by:
 - A Statement pursuant to 37 C.F.R. §1.97(e) or
 - The fee set forth in 37 C.F.R. §1.17(p), believed to be _____.
 - Before payment of the Issue Fee. The Statement is accompanied by:
 - A Statement pursuant to 37 C.F.R. §1.97(e) and
 - The fee set forth in 37 C.F.R. §1.17(p), believed to be _____.

I. Provision of Copies

- A copy of each of the references listed on the attached Form PTO Form 1449 is enclosed herewith and forms a part hereof.
- A translation of References AA, AB and AC are enclosed herewith and form a part hereof.
- A copy of the European Search Report from a corresponding or related EPO application is enclosed herewith.
- A copy of the International Search Report from a corresponding or related PCT application is enclosed herewith.
- This application claims priority, pursuant to 35 U.S.C. §120, to prior U.S. Application No. _____, filed _____. References not submitted herewith were submitted to or cited by the Office in the prior application(s).

II. Fee

No fee is believed due in connection with filing of this Statement. However, in the event a fee or refund is due, the Commissioner is authorized to charge any fee associated with this communication or credit any overpayment to Deposit Account No. 04-1679 (N1085-00151).

The fee in the amount \$ _____ that is due in connection of filing of this Statement was paid upon electronic filing of a corresponding Statement, which was made on _____ using the ePAVE software.

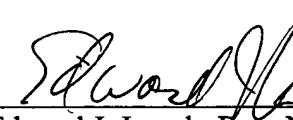
The fee set forth in 37 C.F.R. §1.17(p), believed to be \$ _____, is believed to be due in connection of filing of this Statement.

A check in the amount \$ _____ is enclosed.

The Commissioner is authorized to charge any other fee associated with this communication, or credit any overpayment, to Deposit Account No. 04-1679 (N1085-00151).

Respectfully submitted,

Dated: Apr 8, 2004



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<p>Form PTO-1449 Modified U.S. Patent and Trademark Office</p> <p>List of Patent and Publications Cited by Applicant (Use several sheets if necessary)</p> <p>U.S. Department of Commerce Patent and Trademark Office</p>	Docket No. N1085-00151(TSMC2003-0025)	Serial No. 10/627,849
	Applicant Chien-Chao Huang et al.	
	Filing Date 07/25/2003	Confirmation No. 2641

U. S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS

Examiner Initial	Cite No.	(Include name of author in CAPITAL LETTERS, Title of the Article (when appropriate) title of the item (book, magazine, journal, symposium, catalog, etc.) date, pages, volume, issue number(s), publisher, city and/or country where published)	T
	1	Ootsuka, F., et al., "A Highly Dense, High-Performance 130nm node CMOS Technology for Large Scale System-on-a-Chip Applications", IDEM 00, IEEE 0-7803-6438, (APR 2000), pp. 575-578	
	2	Tiwari, S., et al. "Hole Mobility Improvement in Silicon-on-Insulator and Bulk Silicon Transistors Using Local Strain", IDEM 97, (APR 2000), pp. 939-941	

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.